



Serial No. 10/731,453  
Attorney Docket No. 11948.0025

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application:  
Rajeev Joshi et al.

Serial No.: 10/731,453

Filed: December 9, 2003

For: WAFER-LEVEL CHIP SCALE PACKAGE AND  
METHOD FOR FABRICATING AND USING THE  
SAME

Confirmation No. 4432

Group Art Unit: 2891

Examiner: Zarnecke, David A.

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

**AMENDMENT AND REQUEST FOR RECONSIDERATION**  
**UNDER 37 C.F.R. §§ 1.111 & 1.115**

In response to the Office Action mailed on June 12, 2006, Applicant requests reconsideration of this application in light of the following remarks.

**Amendments to the Specification** are reflected in the list of claims that begins on page 2 of this paper.

**Remarks** begin on page 3 of this paper.

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to:  
Commissioner for Patents, Alexandria, VA 22313-1450, on this 10<sup>th</sup> day of  
September 2006.

Signed: \_\_\_\_\_

9/6/2006